



Volume IX

May 1, 2015

Welcome to Solutions Newsletter. This periodic newsletter provides information on our latest happenings and product updates.

Many thanks to our loyal customers for their continued interest in our products.

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Solutions Newsletter

For Dispense and Assembly

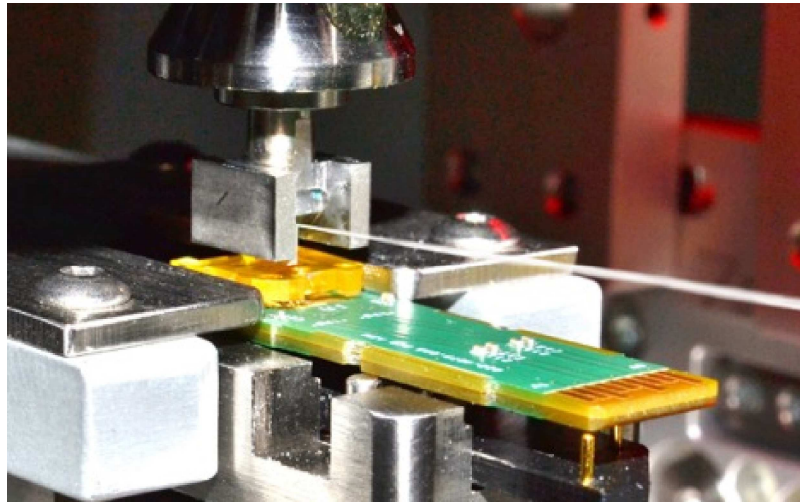
AOC Die Bonder Integrated with In Situ Light Measurement

Provides Built in Quality Assurance

One challenge in building photonic devices, such as Active Optical Cables (AOC), is to ensure proper light coupling as early in the manufacturing process as possible. This direct feedback ensures product integrity and increases product yield by providing immediate feedback during assembly.

The overall process begins with the placement of the die on an AOC board. For a board which contains an optical transmitter and receiver this assembly normally consist of a VECSEL array, photo detector array, TIA and driver chip. The MRSI-M3 Ultra Precision Assembly Work Cell first performs vision alignment, then dispenses conductive epoxy, and finally places the devices with 3 micron or better placement accuracy.

Following thermal curing and wire bonding, the MRSI-M3 performs vision alignment, dispenses UV and thermal cure epoxy, and then attaches the lens. While holding the lens in place the system measures the light output from the pre-characterized device. This measurement process can also be done post UV and thermal cure to characterize any shift due to epoxy curing.



Join us at IEEE IMS & ECTC Shows

We hope to see you at the trade show!

We are exhibiting at the IEEE MMTS Microwave Symposium in Phoenix, Arizona on May 17-22, booth #3618. The Exhibition consists of over 550 exhibitors who represent the state-of-the-art when it comes to materials, devices, components, and subsystems, as well as design and simulation software and equipment.

The following week of May 26th - 29th 2015, we are exhibiting at the 65th Electronic Components and Technology Conference (ECTC) booth #503. ECTC is the premier international event that brings together the best in packaging, components and microelectronic systems science, technology and education in an environment of cooperation and technical exchange. ECTC is sponsored by the Components, Packaging and Manufacturing Technology (CPMT) Society of the IEEE. The 2015 ECTC will be held at the Sheraton San Diego Hotel & Marina, San Diego, California, USA.

You are always welcome to come visit us at our Billerica factory. Contact us with your dispensing and assembly challenges. Chances are we have already solved them!



MRSI - M3
Assembly Work Cell



MRSI - M5
Assembly Work Cell



MRSI-705
Assembly Work Cell



MRSI-175Ag
Epoxy Dispenser



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